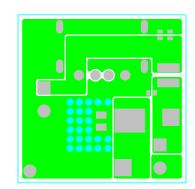
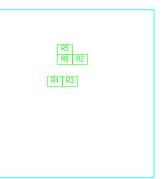


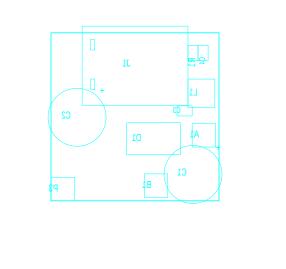
TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Тор	Bot	Тор	Bot	Тор	Bot	Top	Bot	Тор	Bot	T do Didwing
Board No. PMP8363_SEC  Rev.  D		L1											
Date: {Start Date} Filename: {PCB Filename} Engineer: {Name}		P	CB Dsgnr: {Name}	Osgnr: {Name} Modified Date:				Date: {Modification Date}					



	TEXAS INSTRUMENTS			Copper Layer Nar		yer Name	Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
				Тор		Bot	Top	Bot	Тор	Bot	Top	Bot	Top	Bot	T ab Drawing
	PMP8363_SEC Rev.				L2										
	Date: {Start Date} Filename: {PCB Filename} Engineer: {Name}			PCB Dsgnr: {Name} Modified Date:				e: {Modification Date}						Software PADs v9.2	



Г	TEXAS INSTRUMENTS			Copper Layer Name		S	Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
L				Тор	Bot	To	op	Bot	Тор	Bot	Top	Bot	Тор	Bot	T ab blawing
	Board No. PMP83	363_SEC	Rev. D	L1									TA		
D	Date: {Start Date} Filename: {PCB Filename} Engineer: {Name}			PCB Dsgnr: {Name}			ed Date: {	Modification	Date}				Software	PADs v9.2	



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
TEXAS INSTRUMENTS		Тор	Bot	Тор	Bot	Тор	Bot	Top	Bot	Тор	Bot	T ab brawing
Board No. Rev. D			L2								BA	
Date: {Start Date} Filename: {PCB Filename} Engineer: {Name}		PCI	B Dsgnr: {Name}	Modified Date: {Modification Date}							Software PADs v9.2	

## NOTES: UNLESS OTHERWISE SPECIFIED 1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LARTED TO BASE LAMINATE, BOYLONG MATERIALS AND SACREMAKE COMMISS FORMING THE PROPRIED PROTTED DROTT BURING SMALL MICE.

		UL-786 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABLITY OF UL94V-0.  PLASTIC SHEET, LAMINATED METAL CLAD. ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR
2.	BASE LAMINATE:	EQUIVALENT, WITg =140 Deg C OR HIGHER MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPONY RESIN, COPPER CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3.	SOLDERMASK:	SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDINACE WITH IPC SMIBIO, COLOR: GREEN, MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4.	TOLERANCES:	UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/005 INCHES, HOLE DIAMETERS SHALL BE +/003 INCHES.
5.	PLATING:	HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THICK MIN. THICK COPPER.
6.	FINSH	PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/AgiCu, WITH RIAN ELUX, 0.0037 to 0.0037 TING ALL EXPOSED A REAS AS CALAIED, NO ACKIVE FLUXIES ARE ACCEPTABLE.
7.	LEGEND:	IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8.	MARKINGS:	BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9.	WORKMANSHIP:	BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10.	DOCUMENTATION:	PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11.	DRILL SIZES:	HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12.	PANEL BORDER:	ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13	PROCESS CHANGES:	NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION

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